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Specification							
Part Number:							
Version:							
Date:							
Revision							

# **Contents**

- 1.General Specification
- 2. Module Classification Information
- 3.Interface Pin Function
- 4. Contour Drawing & Block Diagram
- 5. Character Generator ROM Pattern
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### Midas LCD Part Number System

```
COG
                 132033
                                Α
                                               6
                                                                                 S
                                                                                               T
 1
          2
                                 4
                                        5
                                              6
                                                     7
                                                            8
                                                                   9
                                                                                       11
                                                                                              12
                      3
                                                                                10
                                                                                                      13
                                                                                                                    15
                                                                                                             14
                                                                                                                           16
1
                   MC: Midas Components
2
                   Blank: COB (chip on board) COG: chip on glass
3
         =
                   No of dots
                                      (e.g. 240064 = 240 \times 64 \text{ dots})
                                                                            (e.g. 21605 = 2 \times 16 5 mm C.H.)
                   Series
4
                   Series Variant:
                                      A to Z - see addendum
5
                   3: 3 o'clock
                                      6: 6 o'clock
                                                         9: 9 o'clock
                                                                            12: 12 o'clock
6
7
                   S: Normal (0 to + 50 deg C) W: Wide temp. (-20 to + 70 deg C) X: Extended temp (-30 + 80 Deg C)
8
                   Character Set
                   Blank: Standard (English/Japanese)
                   C: Chinese Simplified (Graphic Displays only)
                   CB: Chinese Big 5 (Graphic Displays only)
                   H: Hebrew
                   K: European (std) (English/German/French/Greek)
                   L: English/Japanese (special)
                   M: European (English/Scandinavian)
                   R: Cyrillic
                   W: European (English/Greek)
                   U: European (English/Scandinavian/Icelandic)
                   J: Asian/Arabic
         =
9
                   Bezel Height (where applicable / available)
                                                      Common
                                                                     Array
                             Top of Bezel to Top
                                                      (via pins 1
                                                                    or Edge
                                   of PCB
                                                        and 2)
                                                                      Lit
                             9.5mm / not
                    Blank
                                                      Common
                                                                     Array
                             applicable
                    2
                             8.9 \text{ mm}
                                                      Common
                                                                     Array
                    3
                             7.8 \; \mathrm{mm}
                                                      Separate
                                                                     Array
                    4
                             7.8 \ \mathrm{mm}
                                                      Common
                                                                     Array
                    5
                             9.5 \text{ mm}
                                                      Separate
                                                                     Array
                    6
                                                      Common
                                                                     Array
                             7 \text{ mm}
                    7
                             7~\mathrm{mm}
                                                      Separate
                                                                     Array
                    8
                                                                     Edge
                             6.4 \text{ mm}
                                                      Common
                    9
                             6.4 \text{ mm}
                                                      Separate
                                                                     Edge
                                                                     Edge
                    A
                             5.5 \text{ mm}
                                                      Common
                    В
                             5.5 \text{ mm}
                                                      Separate
                                                                     Edge
                    D
                             6.0mm
                                                                     Edge
                                                      Separate
                    \mathbf{E}
                             5.0mm
                                                       Separate
                                                                     Edge
                                                                     Edge
                    F
                             4.7mm
                                                      Common
                    G
                             3.7mm
                                                      Separate
                                                                      \mathbf{EL}
10
                   T: TN S: STN B: STN Blue G: STN Grey F: FSTN F2: FFSTN V: VATN Z: Zero Power (Bi-Stable)
         =
         =
                   P: Positive N: Negative
11
12
         =
                   R: Reflective M: Transmissive T: Transflective
13
                   Backlight: Blank: Reflective L: LED
                   Backlight Colour: Y: Yellow-Green W: White B: Blue R: Red A: Amber O: Orange G: Green RGB: R.G.B.
14
                   If Z (Zero Power): WB: White on blue GB: Green on black YB: Yellow on black YPB: Yellow on pink and/or blue
         =
                   Driver Chip:
                                      Blank: Standard I: I<sup>2</sup>C T: Toshiba T6963C A: Avant SAP1024B R: Raio RA8835
15
```

Voltage Variant: e.g. 3 = 3v

## 1.General Specification

The Features is described as follow:

■ Module dimension: 87.0 x 60.0 x 13.6 (max.) mm

■ View area: 62.0 x 26.0 mm

■ Active area: 56.2 x 20.8 mm

■ Number of Characters: 16 characters x 4 Lines

■ Dot size: 0.55 x 0.55 mm

■ Dot pitch: 0.60 x 0.60 mm

■ Character size: 2.95 x 4.75 mm

■ Character pitch: 3.55 x 5.35 mm

■ LCD type: VA Negative Transmissive

■ Duty: 1/16

■ View direction: 12 o'clock

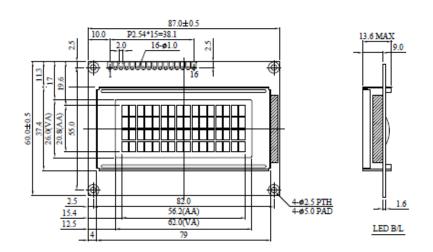
■ Backlight Type: LED, Blue (High light )

■ IC:RW1063

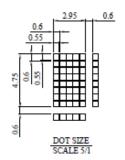
# 3.Interface Pin Function

Pin No.	Symbol	Level	Description
1	V <sub>SS</sub>	0V	Ground
2	$V_{DD}$	5.0V	Supply Voltage for logic
3	VO	(Variable)	Contrast Adjustment
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read (Module> MPU) L: Write(MPU> Module)
6	Е	H,H→L	Chip enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line
15	Vee	_	Negative Voltage Output
16	K	_	LED -

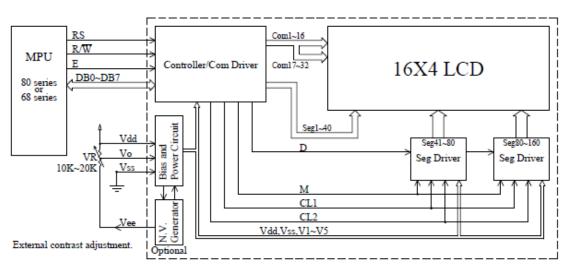
# 4. Contour Drawing & Block Diagram



PIN NO.	SYMBOL
1	Vss
2	Vdd
3	Vo
4	RS
5	R/W
6	E
7	DB0
8	DB1
9	DB2
10	DB3
11	DB4
12	DB5
13	DB6
14	DB7
15	Vee
16	K



The non-specified tolerance of dimension is  $\pm 0.3$ mm.



Character located DDRAM address DDRAM address DDRAM address DDRAM address

1	2	3	4	5	6	7	8	-						15	
00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F
														4E	
														1E	
50	51	52	53	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F

# **5.Character Generator ROM Pattern**

Table.2

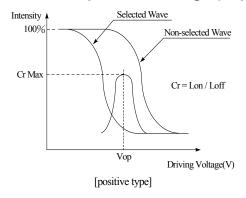
I able	·. <b>_</b>														
<u>b7≈4</u> b3≈0	0000	0001	0010	0011	0100		0110	0111	1000	1001	1010	1011	110 <b>1</b>	1110	1111
0000	[00]													œ	
0001	CG RAM [01]														
0010	[02]														
0011	CG RAM [03]														
0100	[04]														
0101	CG RAM [05]														
0110	CG RAM [06]													P	
0111	CG RAM [07]														
1000	C6 RAM [00]														
1001	CG RAM [01]														
1010	CG RAM [02]														
1011	CG RAM [03]														
1100	CG RAM [04]					Ħ								\$	
1101	CG RAM [05]														
1110	CG RAM [06]														
1111	CG RAM [07]														

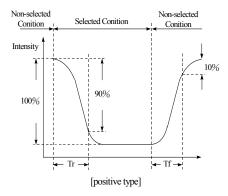
# **6.Optical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧10	_	60	_	ψ= 180°
View Angle	θ	CR≧10	_	25	_	ψ= 0°
View Angle	θ	CR≧10	_	40	_	ψ= 90°
	θ	CR≧10	_	40	_	ψ= 270°
Contrast Ratio	CR	_	10	_	_	_
Doononee Time	T rise	_	_	300	350	ms
Response Time	T fall	_	_	300	350	ms

### **Definition of Operation Voltage (Vop)**

### Definition of Response Time ( Tr , Tf )



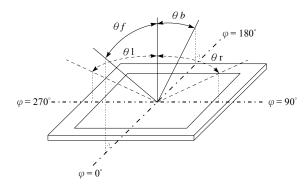


#### **Conditions:**

Operating Voltage : Vop Viewing Angle( $\theta$ ,  $\phi$ ) :  $0^{\circ}$ ,  $0^{\circ}$ 

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

### **Definition of viewing angle(CR≥2)**



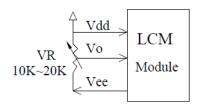
# 7. Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T <sub>OP</sub>	-20	_	+70	
Storage Temperature	T <sub>ST</sub>	-30	_	+80	
Input Voltage	V <sub>IN</sub>	-0.3	_	V <sub>DD</sub> +0.3	V
Supply Voltage For Logic	VDD-V <sub>SS</sub>	-0.3	_	5.5	V
Supply Voltage For LCD	$V_{DD}$ - $V_0$	V <sub>SS</sub> -0.3	_	V <sub>SS</sub> +7.0	V

## **8. Electrical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$V_{DD}$ - $V_{SS}$	_	4.5	5.0	5.5	V
Supply Voltage For LCD		Ta=-20	_	_	_	V
*Note	$V_{OP}$	Ta=25	6.2	6.5	6.8	V
		Ta=70	_	_	_	V
Input High Volt.	V <sub>IH</sub>	_	2.5	_	$V_{DD}$	V
Input Low Volt.	V <sub>IL</sub>	_	-0.3	_	0.6	V
Output High Volt.	V <sub>OH</sub>	_	3.9	_	_	V
Output Low Volt.	V <sub>OL</sub>	_	_	_	0.4	V
Supply Current	I <sub>DD</sub>	V <sub>DD</sub> =5.0V		3.0	_	mA

<sup>\*</sup> Note: Please design the VOP adjustment circuit on customer's main board



# 9.Backlight Information

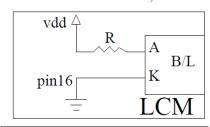
### **Specification**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	_	128	160	mA	V=5.0V
Supply Voltage	V	4.9	5.0	5.1	v	_
Reverse Voltage	VR	_	_	5	v	_
Luminance (Without LCD)	IV	180	230	_	CD/M <sup>2</sup>	ILED=128mA
Wave Length	λр	465	_	477	nm	ILED=128mA
Life Time	_	_	20K	_	Hr.	ILED=128mA 25 ,50-60%RH
Color	High light	Blue				

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:20K hours is only an estimate for reference.

Drive from Vdd, Pin 16



## 10.Reliability

### Content of Reliability Test (Wide temperature, -20 ~70 )

Environmental Test										
Test Item	Content of Test	Test Condition	Note							
High Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	2							
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30 200hrs	1,2							
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70 200hrs								
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20 200hrs	1							
High Temperature/ Humidity storage	The module should be allowed to stand at 60 ,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60 ,90%RH 96hrs	1,2							
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20 25 70	-20 /70 10 cycles								
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3							
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time								

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

# 11.Inspection specification

NO	Item			Criterion		AQL		
01	Electrical Testing	defect. 1.2 Missing char 1.3 Display malf 1.4 No function 1.5 Current cons 1.6 LCD viewing 1.7 Mixed produ	1.2 Missing character, dot or icon.  1.3 Display malfunction.  1.4 No function or no display.  1.5 Current consumption exceeds product specifications.  1.6 LCD viewing angle defect.  1.7 Mixed product types.  1.8 Contrast defect.					
02	Black or white spots on LCD (display only)	three white o	<ul><li>2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.</li><li>2.2 Densely spaced: No more than two spots or lines within 3mm</li></ul>					
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type $\Phi = (x + y) / $ $\longrightarrow X$ $\longrightarrow $	<sup>2</sup> ↓ Y	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense  2 1 0  Acceptable Q TY Acceptable Q TY Accept no dense  2 As round type	2.5		
04	Polarizer bubbles	If bubbles are vi judge using blac specifications, n to find, must che specify direction	ck spot ot easy eck in	Size $\Phi$ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5		

NO	Item		Criterion								
05	Scratches	Follow NO.3 LCD black	spots, white spots, con	tamination							
		Symbols Define:									
		x: Chip length y: 0	Chip width z: Chip	thickness							
		k: Seal width t: Glass thickness a: LCD side length									
		L: Electrode pad length:									
		6.1 General glass chip									
		6.1.1 Chip on panel sur	face and crack betweer	n panels:							
		z: Chip thickness	y: Chip width	x: Chip length							
		Z≦1/2t	Not over viewing	x≦1/8a							
06	Chipped		area		2.5						
	glass	1/2t <z≦2t< td=""><td>Not exceed 1/3k</td><td>x≦1/8a</td><td></td></z≦2t<>	Not exceed 1/3k	x≦1/8a							
		⊙ If there are 2 or more chips, x is total length of each chip.									
		6.1.2 Corner crack:	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	y							
		z: Chip thickness	y: Chip width	x: Chip length							
		Z≦1/2t	Not over viewing area	x≦1/8a							
		1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a							
		⊙ If there are 2 or more	chips, x is the total leng	gth of each chip.							

NO	Item		Criterion		AQL
06	Glass crack	y: Chip width y≤0.5mm 6.2.2 Non-conductive port	x≦1/8a	: Chip thickness $0 < z \le t$	2.5
		must remain and specifications.	x≤1/8a  a touches the ITO termina be inspected according to be heat sealed by the cus aged.	electrode terminal	

Cracked glass   The LCD with extensive crack is not acceptable.   2.5	NO	Item	Criterion	AQL					
Backlight elements  8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.  9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.  10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB  11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 2.5	07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5					
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seal area on the PCB. And there should be no more than three places.  10.5 No oxidation or contamination PCB terminals.  10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.  10.7 The jumper on the PCB should conform to the product characteristic chart.  10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.  10.9 The Scraping testing standard for Copper Coating of PCB  2.5  2.5  2.5  3.665  3.665  3.665  3.665  3.665  3.665  3.665  3.665  3.665  3.665  3.665  3.665  3.665  3.665  3.665  3.65  3.665									
10 PCB · COB  10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.  10.7 The jumper on the PCB should conform to the product characteristic chart.  10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.  10.9 The Scraping testing standard for Copper Coating of PCB  2.5  2.5  2.5  11.1 No un-melted solder paste may be present on the PCB.  11.2 No cold solder joints, missing solder connections, oxidation or icicle.  11.3 No residue or solder balls on PCB.  2.5			seal area on the PCB. And there should be no more than	2.5					
characteristic chart. There should be no wrong parts, missing parts or excess parts.  10.7 The jumper on the PCB should conform to the product characteristic chart.  10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.  10.9 The Scraping testing standard for Copper Coating of PCB  2.5  2.5  2.5  3.665  3.65  3			10.5 No oxidation or contamination PCB terminals.						
missing parts or excess parts.  10.7 The jumper on the PCB should conform to the product characteristic chart.  10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.  10.9 The Scraping testing standard for Copper Coating of PCB  2.5  X * Y<=2mm2  11.1 No un-melted solder paste may be present on the PCB.  11.2 No cold solder joints, missing solder connections, oxidation or icicle.  11.3 No residue or solder balls on PCB.  2.5	10	PCB · COB	·	2.5					
characteristic chart.  10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.  10.9 The Scraping testing standard for Copper Coating of PCB  2.5  2.5  11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 2.5			<u> </u>	0.65					
10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.  10.9 The Scraping testing standard for Copper Coating of PCB  2.5  2.5  11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 2.5									
10.9 The Scraping testing standard for Copper Coating of PCB  2.5  X * Y<=2mm2  11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 2.5  2.5  2.5  2.5  2.5  2.5  2.5  2.			10.8 If solder gets on bezel tab pads, LED pad, zebra pad or	0.65					
X * Y<=2mm2  11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 2.5 2.5 2.5			·	2.5					
11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 2.5			X X * Y<=2mm2	2.5					
11 Soldering or icicle. 11.3 No residue or solder balls on PCB. 2.5			11.1 No un-melted solder paste may be present on the PCB.	2.5					
11.3 No residue or solder balls on PCB. 2.5	44	0-14		2.5					
	11	Soldering		2.5					
The five short direction in components on FOD. 10.00			11.4 No short circuits in components on PCB.	0.65					

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
		pin must be present or look as if it cause the interface pin to	
	General	sever.	2.5
12	appearance	12.6 The residual rosin or tin oil of soldering (component or chip	
	appeararies	component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on	0.00
		packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65
		12.12 Visual defect outside of VA is not considered to be rejection.	

### 12. Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Midas have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)Midas have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Midas have the right to modify the version.)

# 13. Material List of Components for RoHs

1. Midas Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs				
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm				
Above limited value is set up according to RoHS.										

#### 2.Process for RoHS requirement:

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp.:

Reflow: 250 ,30 seconds Max.;

Connector soldering wave or hand soldering: 320, 10 seconds max.

(3) Temp. curve of reflow, max. Temp.: 235±5;

Recommended customer's soldering temp. of connector: 280, 3 seconds.

# 14. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.

### 15.Other (IC Information)

### **1.Function Description**

#### **SYSTEM INTERFACE (Parallel 8-bit bus and 4-bit bus)**

This chip has all four kinds interface type with MPU: IIC, 4SPI, 4-bit bus and 8-bit bus. Serial and parallel buses (4-bit/8-bit) are selected by IF1 and IF0 input pins, and 4-bit bus and 8-bit bus is selected by DL bit in the instruction register.

During read or write operation, two 8-bit registers are used. One is data register (DR); the other is instruction register (IR). The data register (DR) is used as temporary data storage place for being written into or read from DDRAM/CGRAM, target RAM is selected by RAM address setting instruction. Each internal operation, reading from or writing into RAM, is done automatically. So to speak, after MPU reads DR data, the data in the next DDRAM/CGRAM address is transferred into DR automatically. Also after MPU writes data to DR, the data in DR is transferred into DDRAM/CGRAM automatically.

The Instruction register (IR) is used only to store instruction code transferred from MPU. MPU cannot use it to read instruction data.

IR: Instruction Register.

DR: Data Register.

RS	R/W	Operation
0	0	Instruction write operation (MPU writes Instruction code into IR)
0	1	Read busy flag (DB7) and address counter (DB0 - DB6)
1	0	Data write operation (MPU writes data into DR
1	1	Data read operation (MPU reads data from DR)

#### **BUSY FLAG (BF) (only support parallel 8-bit bus and 4-bit bus)**

When BF = "High", it indicates that the internal operation is being processed. So during this time the next instruction cannot be accepted. BF can be read, when RS = Low and R / W = High (Read Instruction Operation); through DB7 before executing the next instruction, be sure that BF is not High.

#### **DISPLAY DATA RAM (DDRAM)**

DDRAM stores display data of maximum 80 x 8 bits (80 characters). DDRAM address is set in the address counter (AC) as a hexadecimal number. (Refer to Figure 1.)



Figure 1 DDRAM Address

Since DDRAM has 8 bits data. It is possible to access 256 CGROM/CGRAM fonts.

#### 1-line display (N = 0) (Figure 2)

When there are fewer than 80 display characters, the display begins at the head position. For example, if using only the Controller, 8 characters are displayed. See Figure 3.

When the display shift operation is performed, the DDRAM address shifts. See Figure 3.

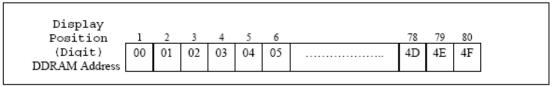


Figure 2 1-Line Display

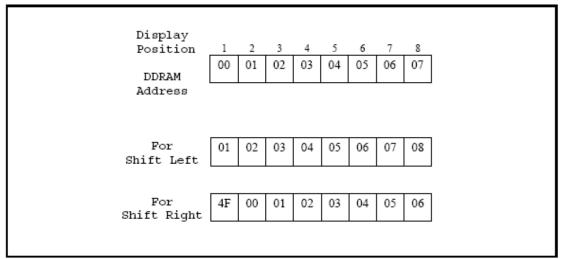


Figure 3 1-Line by 8-Character Display Example

#### 2-line display (N = 1) (Figure 4)

Case 1: When the number of display characters is less than  $40 \times 2$  lines, the two lines are displayed from the head. Note that the first line end address and the second line start address are not consecutive. For example, when just the Controller is used, 8 characters  $\times$  2 lines are displayed. See Figure 5.

When display shift operation is performed, the DDRAM address shifts. See Figure 5.

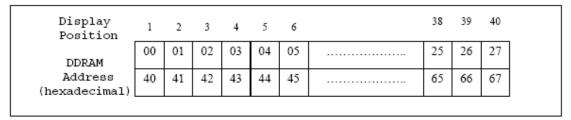


Figure 4 2-Lines Display

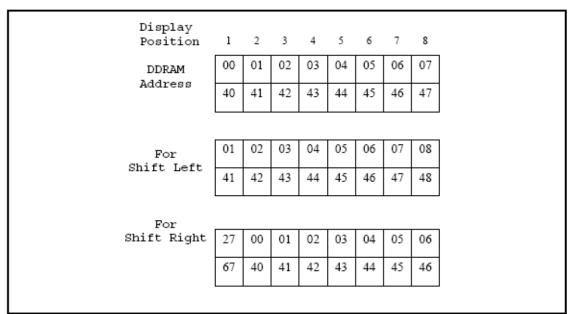


Figure 5 2-Lines by 8-Character Display Example

Case 2: For a 16-character x 2-line display, the Controller can be extended using one 40-output extension driver. See Figure 6.

When display shift operation is performed, the DDRAM address shifts. See Figure 6.

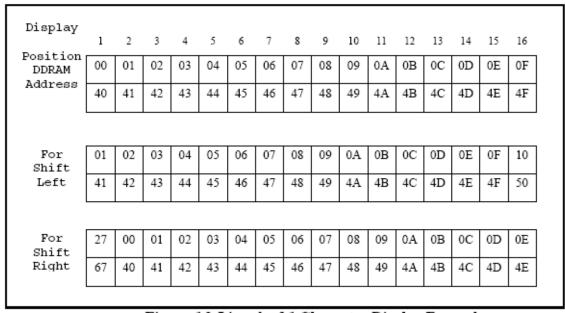


Figure 6 2-Lines by 16-Character Display Example

#### **TIMING GENERATION CIRCUIT**

Timing generation circuit generates clock signals for the internal operations.

### **ADDRESS COUNTER (AC)**

Address Counter (AC) stores DDRAM/CGRAM address, transferred from IR.

After writing into (reading from) DDRAM/CGRAM/SEGRAM, AC is automatically increased (decreased) by 1.

When RS = "Low" and R/W = "High", AC can be read through DB0-DB6

#### **CURSOR/BLINK CONTROL CIRCUIT**

It controls cursor/blink ON/OFF and black/white inversion at cursor position.

#### LCD DRIVER CIRCUIT

LCD Driver circuit has 16 common and 40 segment signals for 2-line display (N=1) or 8 common and 40 segments for 1-line display (N=0) for LCD driving.

Data from CGRAM/CGROM is transferred to 40 bit segment latches serially, and then it is stored to 40 bit shift latch.

#### **CGROM (CHARACTER GENERATOR ROM)**

CGROM has 10,240 bits (256 characters x 5 x 8 dot)

#### **CGRAM (CHARACTER GENERATOR RAM)**

CGRAM has up to 5 8 dots 8 characters. By writing font data to CGRAM, user defined character can be used (refer to Table 2).

#### 5 x 8 dots Character Pattern

Table 2. Relationship between Character Code (DDRAM) and Character Pattern (CGRAM)

	Char	acter	Code	(DD	RAM	[ data	1)	CGRAM Address				CGRAM Data					Pattern					
D7	D6	D5	D4	D3	D2	D1	D0	Α5	Α4	А3	Α2	Α1	A0	P7	P6	P5	P4	Р3	P2	P1	P0	Number
0	0	0	0	0	0	0	0	0	0	0	0	0	0	Χ	Х	Х	0	1	1	1	0	Pattern 1
-	-	-	-	-	0	0	0	-	-	-	0	0	1	-	-	-	1	0	0	0	1	
-	-	-	-	-	0	0	0	-	-	-	0	1	0	-	-	-	1	0	0	0	1	
-	-	-	-	-	0	0	0	-	-	-	0	1	1	-	-	-	1	1	1	1	1	
-	-	-	-	-	0	0	0	-	-	-	1	0	0	-	-	-	1	0	0	0	1	
-	-	-	-	-	0	0	0	-	-	-	1	0	1	-	-	-	1	0	0	0	1	
-	-	-	-	-	0	0	0	-	-	-	1	1	0	-	-	-	1	0	0	0	1	
-	-	-	-	-	0	0	0	ŀ	-	-	1	1	1	-	-	-	0	0	0	0	0	
				-					-			-						-				
				-				L	-			-										
0	0	0	0	0	1	1	1	1	1	1	0	0	0	Х	Х	Х	1	0	0	0	1	Pattern 8
-	-	-	-	-	1	1	1	-	-	-	0	0	1	-	-	-	1	0	0	0	1	
-	-	-	-	-	1	1	1	-	-	-	0	1	0	-	-	-	1	0	0	0	1	
-	-	-	-	-	1	1	1	-	-	-	0	1	1	-	-	-	1	1	1	1	1	
-	-	-	-	-	1	1	1	-	-	-	1	0	0	-	-	-	1	0	0	0	1	
-	-	-	-	-	1	1	1	-	-	-	1	0	1	-	-	-	1	0	0	0	1	
-	-	-	-	-	1	1	1	-	-	-	1	1	0	-	-	-	1	0	0	0	1	
-	-	-	-	-	1	1	1	l -	-	-	1	1	1	-	-	-	0	0	0	0	0	

#### Notes:

- 1. Character code bits 0 to 2 correspond to CGRAM address bits 3 to 5 (3 bits: 8 types).
- 2. CGRAM address bits 0 to 2 designate the character pattern line position. The 8th line is the cursor position and its display is formed by a logical OR with the cursor. Maintain the 8th line data, corresponding to the cursor display position, at 0 as the cursor display. If the 8th line data is 1, 1 bit will light up the 8th line regardless of the cursor presence.

- 3. Character pattern row positions correspond to CGRAM data bits 0 to 4 (bit 4 being at the left).
- 4. As shown Table 2, CGRAM character patterns are selected when character code bits 4 to 7 are all 0 and MW=0. However, since character code bit 3 has no effect, the H display example above can be selected by either character code 00H or 08H.
- 5. 1 for CGRAM data corresponds to display selection and 0 to non-selection.
- "-": Indicates no effect.

## 2.Instruction Table

Instruction	RS	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description	Description Time (540KHz)
Read display data	1	1				Read	data				Read data into DDRAM/CGRAM/SEGRAM	18.5us
Write display data	1	0				Write	e data				Write data into DDRAM/CGRAM/SEGRAM	18.5us
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM, and set DDRAM address to "00H" from AC	0.76ms
Return Home	0	0	0	0	0	0	0	0	1	Х	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	0.76ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	S	Assign cursor moving direction and specify display shift. These operations are performed during data read and write.  I/D="1": increment I/D="0": decrement	18.5us
Display ON/OFF	0	0	0	0	0	0	1	D	С	В	Set Display /Cursor/Blink On/OFF D="1": display on D="0": display off  C="1": cursor on C="0": cursor off  B="1": blink on B="0": blink off	18.5us
Cursor or Display shift	0	0	0	0	0	1	S/C	R/L	X	X	Cursor or display shift S/C="1": display shift S/C="0": cursor shift R/L="1": shift to right R/L="0": shift to left	18.5us
Function Set	0	0	0	0	1	DL	N	F	Х		Set Interface Data Length DL= 8-bit interface/ 4-bit interface N = 2-line/1-line display F= 5x8 Font Size / 5x11Font Size	18.5us
Set CGRAM Address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter	18.5us
Set DDRAM Address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter	18.5us
Read Busy Flag and Address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Can know internal operation is ready or not by reading BF. The contents of address counter can also be read. BF="1": busy state BF="0": ready state	0us

#### **Clear Display**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	_
0	0	0	0	0	0	0	0	0	1	1

Clear all the display data by writing "20H" (space code) to all DDRAM address, and set DDRAM address to "00H" into AC (address counter). Return cursor to the original status; namely, bring the cursor to the left edge on first line of the display. Make entry mode increment (I/D = "1").

#### **Return Home:**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	0	0	1	Х

Return Home is cursor return home instruction. Set DDRAM address to "00H" into the address counter. Return cursor to its original site and return display to its original status, if shifted. A content of DDRAM does not change.

#### **Entry Mode Set:**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	0	1	I/D	S

Set the moving direction of cursor and display.

#### I/D: Increment/decrement of DDRAM address (cursor or blink)

I/D = 1: cursor/blink moves to right and DDRAM address is increased by 1.

I/D = 0: cursor/blink moves to left and DDRAM address is decreased by 1.

\* CGRAM operates the same as DDRAM, when read/write from or to CGRAM

#### S: Shift of entire display

When DDRAM read (CGRAM read/write) operation or S = "Low", shift of entire display is not performed.

If S= "High" and DDRAM write operation, shift of entire display is performed according to I/D value (I/D = "1": shift left, I/D = "0": shift right).

s	I/D	Description
Н	Н	Shift the display to the left
Н	L	Shift the display to the right

#### Display ON/OFF

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	1	D	С	В

Control display/cursor/blink ON/OFF 1 bit register.

#### D: Display ON/OFF control bit.

D = 1: entire display is turned on.

D = 0: display is turned off, but display data is remained in DDRAM.

#### C: Cursor ON/OFF control bit.

C = 1: cursor is turned on.

C = 0: cursor is disappeared in current display, but I/D register remains its data.

#### B: Cursor Blink ON/OFF control bit.

B = 1: cursor blink is on, that performs alternate between all the high data and display character at the cursor position. If fosc has 540 kHz frequency, blinking has 185 ms interval.

B = 0: blink is off.

#### **Cursor or Display Shift**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	1	S/C	R/L	-	-

Without writing or reading of display data, shift right/left cursor position or display. This instruction is used to correct or search display data (refer to Table 4). During 2-line mode display, cursor moves to the 2nd line after 40th digit of 1st line.

Note that display shift is performed simultaneously by the shift enable instruction. When displayed data is shifted repeatedly, all display lines shifted simultaneously. When display shift is performed, the contents of address counter are not changed.

Table 4. Shift Patterns According to S/C and R/L Bits

S/C	R/L	Operation				
0	0	Shift cursor to the left, address counter is decreased by 1				
0	Shift cursor to the right, address counter is increased by 1					
1	0	Shift all the display to the left, cursor moves according to the display				
1	Shift all the display to the right, cursor moves according to the display					

#### **Function Set**

RS	R/V	V DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	DL	N	F	Х	Х

#### DL: Interface data length control bit

When DL = "High", it means 8-bit bus mode with MPU.

When DL = "Low", it means 4-bit bus mode with MPU. So to speak, DL is a signal to select 8-bit or 4-bit bus mode.

When 4-bit bus mode, it needs to transfer 4-bit data by two times.

IF using IIC and 4-SPI interface . DL bit must be setting to "1"

#### N: Display line number control bit

When N = "Low", it means 1-line display mode.

When N = "High", 2-line display mode is set.

#### F: Display font type control bit

When F = "Low", it means 5 x 8 dots format display mode

When F = "High", 5 x11 dots format display mode.

N	F	No. of Display Lines	Character Font	Duty Factor
L	L	1	5x8	1/8
L	Н	1	5x11	1/11
Н	х	2	5x8	1/16

#### **Set CGRAM Address**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0

Set CGRAM address to AC.

This instruction makes CGRAM data available from MPU.

#### **Set DDRAM Address**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0

Set DDRAM address to AC.

This instruction makes DDRAM data available from MPU.

When 1-line display mode (N=0), DDRAM address is from "00H" to "4FH"

In 2-line display mode (NW = 0), DDRAM address in the 1st line is from "00H" - "27H", and DDRAM address in the 2nd line is from "40H" - "67H".

#### **Read Busy Flag and Address** (only support parallel 8-bit bus and 4 bit bus)

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	
0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	1

This instruction shows whether Controller is in internal operation or not. If the resultant BF is "high", it means the internal operation is in progress and you have to wait until BF to be Low, and then the next instruction can be performed. In this instruction you can read also the value of address counter.

#### Write Data to RAM

	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	
- [	1	0	D7	D6	D5	D4	D3	D2	D1	D0	1

Write binary 8-bit data to DDRAM/CGRAM/SEGRAM.

The selection of RAM from DDRAM, CGRAM, is set by the previous address set instruction: DDRAM address set, CGRAM address set. RAM set instruction can also determine the AC direction to RAM.

After write operation, the address is automatically increased/decreased by 1, according to the entry mode.

**Read Data from RAM** (only support parallel 8-bit bus and 4 bit bus)

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	1	D7	D6	D5	D4	D3	D2	D1	D0

Read binary 8-bit data from DDRAM/CGRAM.

The selection of RAM is set by the previous address set instruction. If address set instruction of RAM is not performed before this instruction, the data that read first is invalid, because the direction of AC is not determined.

If you read RAM data several times without RAM address set instruction before read operation, you can get correct RAM data from the second, but the first data would be incorrect, because there is no time margin to transfer RAM data.

In case of DDRAM read operation, cursor shift instruction plays the same role as DDRAM address set instruction: it also transfer RAM data to output data register. After read operation address counter is automatically increased/decreased by 1 according to the entry mode. After CGRAM read operation, display shift may not be executed correctly.

\* In case of RAM write operation, after this AC is increased/decreased by 1 like read operation. In this time, AC indicates the next address position, but you can read only the previous data by read instruction.

#### OUTLINE

To overcome the speed difference between internal clock of Controller and MPU clock, Controller performs internal operation by storing control information to IR (Instruction Register) or DR (data Register).

The internal operation is determined according to the signal from MPU, composed of read/write and data bus.

I Nstruction can be divided largely four kinds;

- \*Controller function set instructions (set display methods, set data length, etc.)
- \*Address set instructions to internal RAM
- \*Data transfer instructions with internal RAM
- \*Others

The address of internal RAM is automatically increased or decreased by 1.

**NOTE:** During internal operation, Busy Flag (DB7) is read high. Busy Flag check must be preceded the next instruction.

Busy flag check must be proceeded the next instruction.

When an MPU program with Busy Flag (DB7) checking is made, 1/2 Fosc (is necessary) for executing the next instruction by the falling edge of the "E" signal after the Busy Flag (DB7) goes to "Low".

#### INTERFACE WITH MPU

Controller can transfer data in bus mode (4-bit or 8-bit) or serial mode with MPU.

In case of 4-bit bus mode, data transfer is performed by two times to transfer 1 byte data.

When interfacing data lengths are 4-bit, only 4 ports, from DB4 - DB7, are used as data bus. At first higher 4-bit (in case of 8-bit bus mode, the contents of DB4 - DB7) are transferred, and then lower 4- bit (in case of 8-bit bus mode, the contents of DB0 - DB3) are transferred. So transfer is performed by two times.

Busy Flag outputs "High" after the second transfer are ended.

When interfacing data length are 8-bit, transfer is performed at a time through 8 ports, from DB0 - DB7.

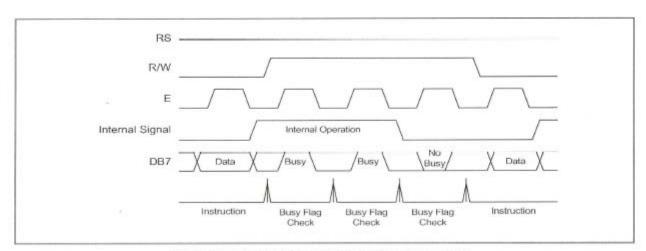
Interface is selected by IF1,IF0 pins (refer to **Bonding Note for IF1, IF0** on Page 10)

IF1	IF0	Interface select
open	open	6800 8/4 bit
open	Bonding to VDD	IIC
Bonding to VDD	open	4-line SPI

#### INTERFACE WITH MPU IN BUS MODE

#### Interface with 8-bit MPU

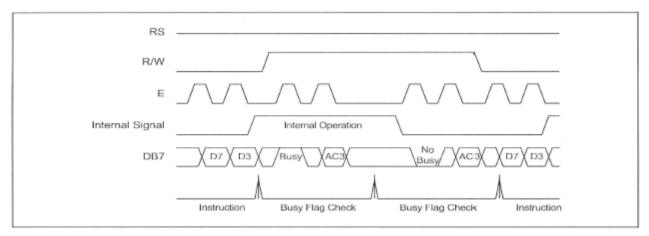
If 8-bits MPU is used, Controller can connect directly with that. In this case, port E, RS, R/W and DB0 to DB7 need to interface each other. Example of timing sequence is shown below.



Example of 8-bit Bus Mode Timing Sequence

#### Interface with 4-bit MPU

If 4-bit MPU is used, Controller can connect directly with this. In this case, port E, RS, R/W and DB4 - DB7 need to interface each other. The transfer is performed by two times. Example of timing sequence is shown below.



Example of 4-bit Bus Mode Timing Sequence

#### INITIALIZING

#### **INITIALIZING BY INTERNAL RESET CIRCUIT**

When the power is turned on, Controller is initialized automatically by power on reset circuit. During the initialization, the following instructions are executed, and BF (Busy Flag) is kept "High" (busy state) to the end of initialization.

### **Clear Display Instruction**

Write "20H" to all DDRAM

#### **Set Functions Instruction**

DL = 1: 8-bit bus mode

N = 0: 1-line display

 $F = 0: 5 \times 8$  dot character font

#### **Display ON/OFF Instruction**

D = 0: Display OFF

C = 0: Cursor OFF

B = 0: Blink OFF

#### **Set Entry Mode Instruction**

I/D = 1: Increment by 1

S = 0: No entire display shift

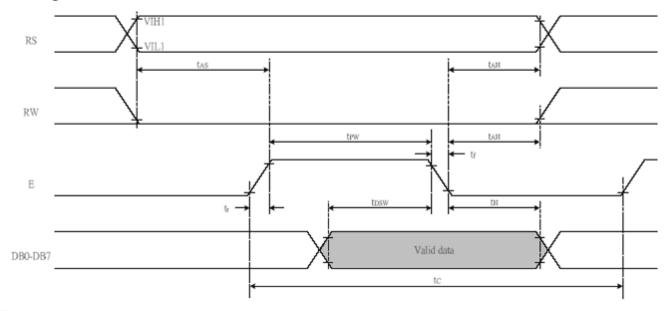
#### Note:

If the electrical characteristics conditions listed under the table Power Supply Conditions Using Internal Reset Circuit are not met, the internal reset circuit will not operate normally and will fail to initialize the Controller. For such a case, initialization must be performed by the MPU as explain by the following figure.

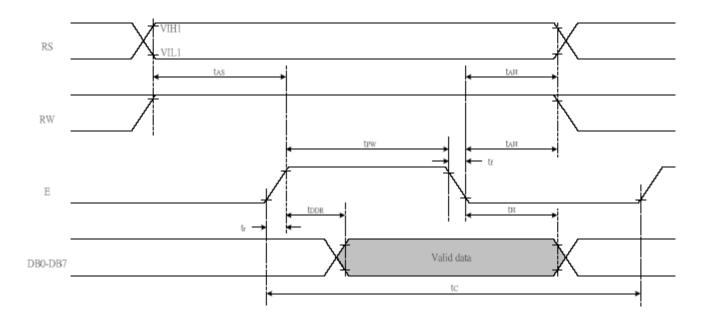
# **3.Timing Characteristics**

### **Timing Characteristics**

Writing data from MPU to IC (Parallel 8-bit bus and 4-bit bus)



### Reading data from IC to MPU(Parallel 8-bit bus and 4-bit bus)



## In 6800 interface (TA = 25 , VDD = 2.7V)

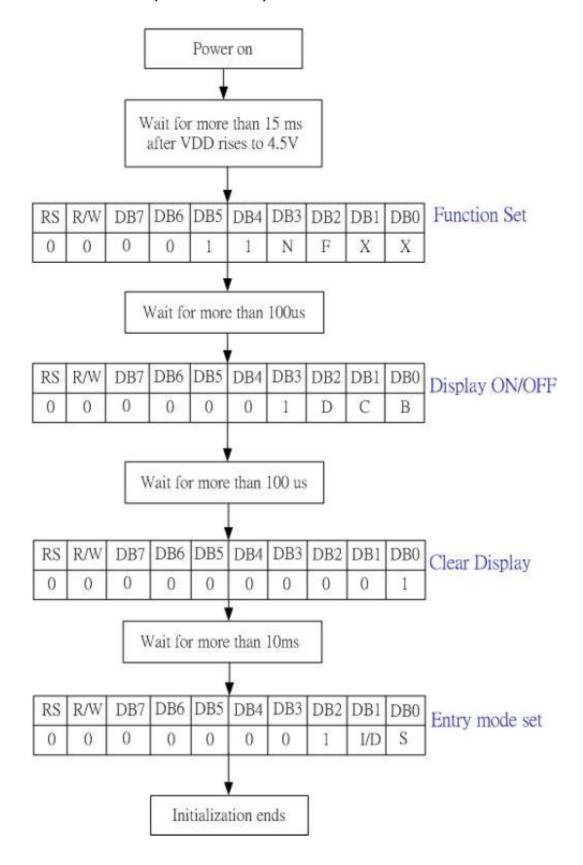
	Write Mode (Writing data from MPU to IC )										
T <sub>C</sub>	Enable Cycle Time	Pin E (except clear display)	1000	-	-	ns					
$T_{\text{PW}}$	Enable Pulse Width	Pin E	450	-	,	ns					
$T_{\mathbb{R}},T_{\mathbb{F}}$	Enable Rise/Fall Time	Pin E	-	-	25	ns					
T <sub>AS</sub>	Address Setup Time	Pins: RS,RW,E	60	-	-	ns					
$T_{AH}$	Address Hold Time	Pins: RS,RW,E	20	-	-	ns					
$T_{\text{DSW}}$	Data Setup Time	Pins: DB0 - DB7	195	•	,	ns					
$T_{\mathrm{H}}$	Data Hold Time	Pins: DB0 - DB7	10	-	,	ns					
	Read Mod	ie (Reading Data from IC to	o MPU)								
Tc	Enable Cycle Time	Pin E	1000	-	,	ns					
$T_{\text{PW}}$	Enable Pulse Width	Pin E	450	,	,	ns					
$T_{\mathbb{R}},T_{\mathbb{F}}$	Enable Rise/Fall Time	Pin E	-	-	25	ns					
T <sub>AS</sub>	Address Setup Time	Pins: RS,RW,E	60	-	-	ns					
$T_{AH}$	Address Hold Time	Pins: RS,RW,E	20	-	-	ns					
$T_{DDR}$	Data Setup Time	Pins: DB0 - DB7	-	-	360	ns					
$T_{\text{H}}$	Data Hold Time	Pins: DB0 - DB7	5	-	-	ns					

## In 6800 interface (TA = 25 , VDD = 5V)

	Waita Ma	de (Writing data from MDI) t	. TC	9		
T <sub>C</sub>	Enable Cycle Time	de (Writing data from MPU t Pin E (except clear display)	500	-	-	ns
$T_{PW}$	Enable Pulse Width	Pin E	230	-	-	ns
$T_R, T_F$	Enable Rise/Fall Time	Pin E	-	-	20	ns
TAS	Address Setup Time	Pins: RS,RW,E	40	-	-	ns
T <sub>AH</sub>	Address Hold Time	Pins: RS,RW,E	10	-	-	ns
$T_{\text{DSW}}$	Data Setup Time	Pins: DB0 - DB7	80	-	-	ns
T <sub>H</sub>	Data Hold Time	Pins: DB0 - DB7	10	-	-	ns
	Read Mod	ie (Reading Data from IC to	MPU)			
$T_{C}$	Enable Cycle Time	Pin E	500	-	-	ns
$T_{PW}$	Enable Pulse Width	Pin E	230	-	-	ns
$T_R, T_F$	Enable Rise/Fall Time	Pin E	-	-	20	ns
T <sub>AS</sub>	Address Setup Time	Pins: RS,RW,E	40	-	-	ns
$T_{AH}$	Address Hold Time	Pins: RS,RW,E	10	-	-	ns
$T_{DDR}$	Data Setup Time	Pins: DB0 - DB7	-	-	120	ns
$T_{\mathtt{H}}$	Data Hold Time	Pins: DB0 - DB7	10	-	-	ns

# 4. Initializing of LCM

#### Serial Interface Mode(Fosc=540KHz)



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